

AMENDMENTS

IN THE CLAIMS:

Cancel Claim 1.

Add new Claims 2-6, as follows:

1 2 A method of making an electronic surface mount package, the method comprising the steps for:

forming a package having a side wall with a bottom end;

encapsulating a plurality of toroid transformers within the package with a resilient material;

molding a plurality of terminal pins within the side wall, each of the pins extending through the side wall and having a solder post end, each of the post ends extending beyond the bottom end of the side wall; and

wrapping and soldering the wires from the transformers to the solder post ends for each of the pins.

2 3 The method of claim 2 wherein the resilient material is a soft silicone material.

3 4 A method of making an electronic surface mount package, the method comprising the steps for:

molding a one piece construction package having a side wall with a bottom end and a plurality of terminal pins within and extending from the bottom of the package;

encapsulating and carrying a plurality of toroid transformers within the package; and

wrapping and soldering the wires from the transformers to an end of a solder post for each of the pins.

4 5 The method of claim 4 wherein the step for encapsulating and carrying the plurality of toroid transformers pours a resilient material into the package and subsequently sets the resilient material.

5 6 The method of claim 5 wherein the resilient material is a soft silicone material.